

NOTES:

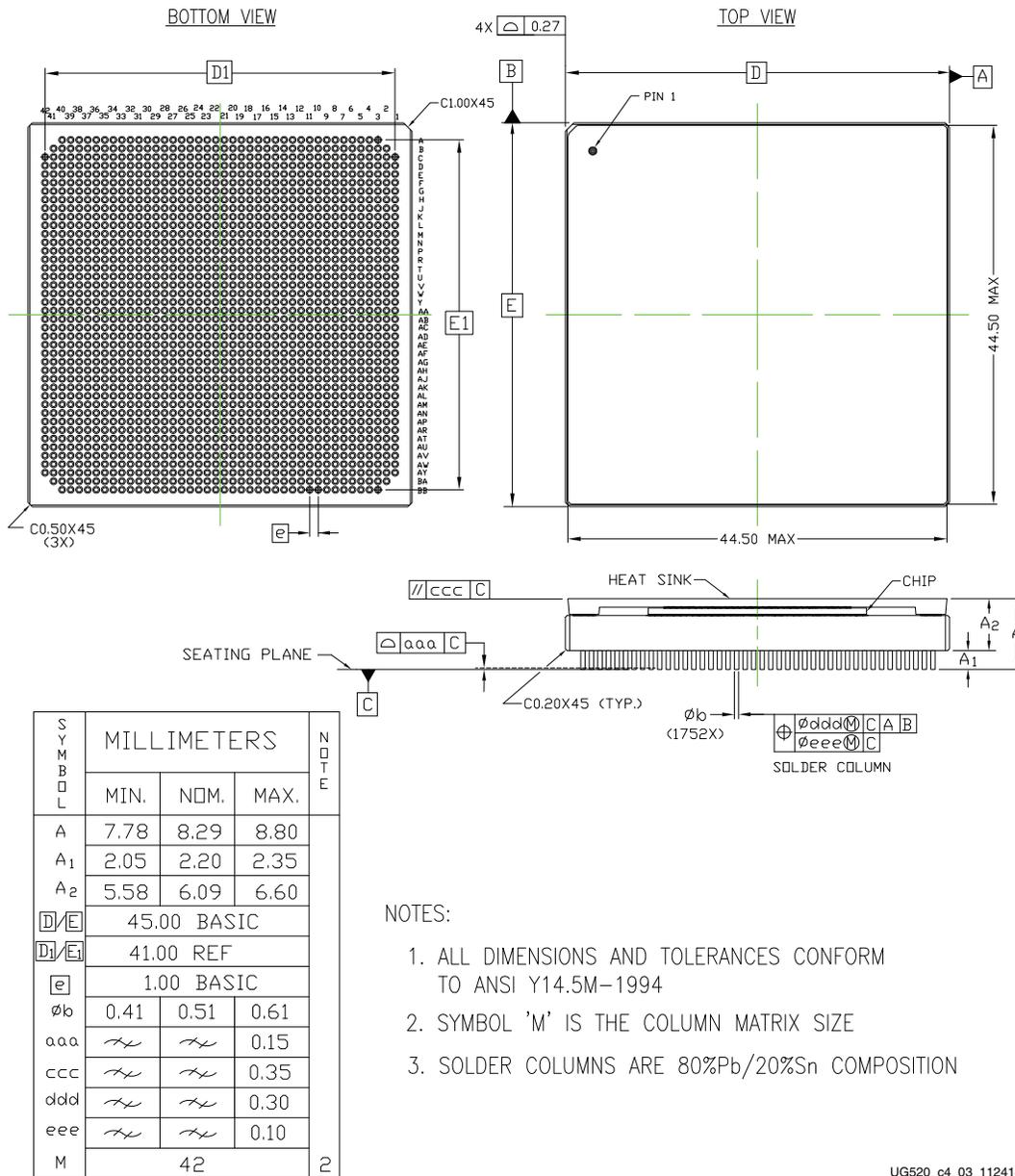
1. THIS PAGE IS TO SHOW THE OPTIONAL LID AND CHIP CAP LOCATIONS.
2. ALL DIMENSIONS ARE THE SAME EXCEPT FOR THE LID.
3. CHIP CAPS: ACCEPTS 0603 (25 PLCS) AND 0805 (6 PLCS)
4. CHIP CAP REFERENCE:
 - (A) - VCCAUX
 - (B) - VCCINT
 - (CN) - VCCO_[1~29] ("N" CORRESPONDS TO BANK NUMBER)
5. CAP PLACEMENT AND QUANTITIES REMAIN THE SAME FOR ALL CF AND CN PACKAGES

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Figure 4-2: CF1752 Ceramic Flip-Chip Column Grid Array Package Mechanical Drawing (32 mm × 25 mm Lid) (This Package is Obsolete per [XCN12020](#))

CN1752 Ceramic Flip-Chip Column Grid Array Package Specifications

CN1752
(WITH SOLDER COLUMNS ATTACHED)

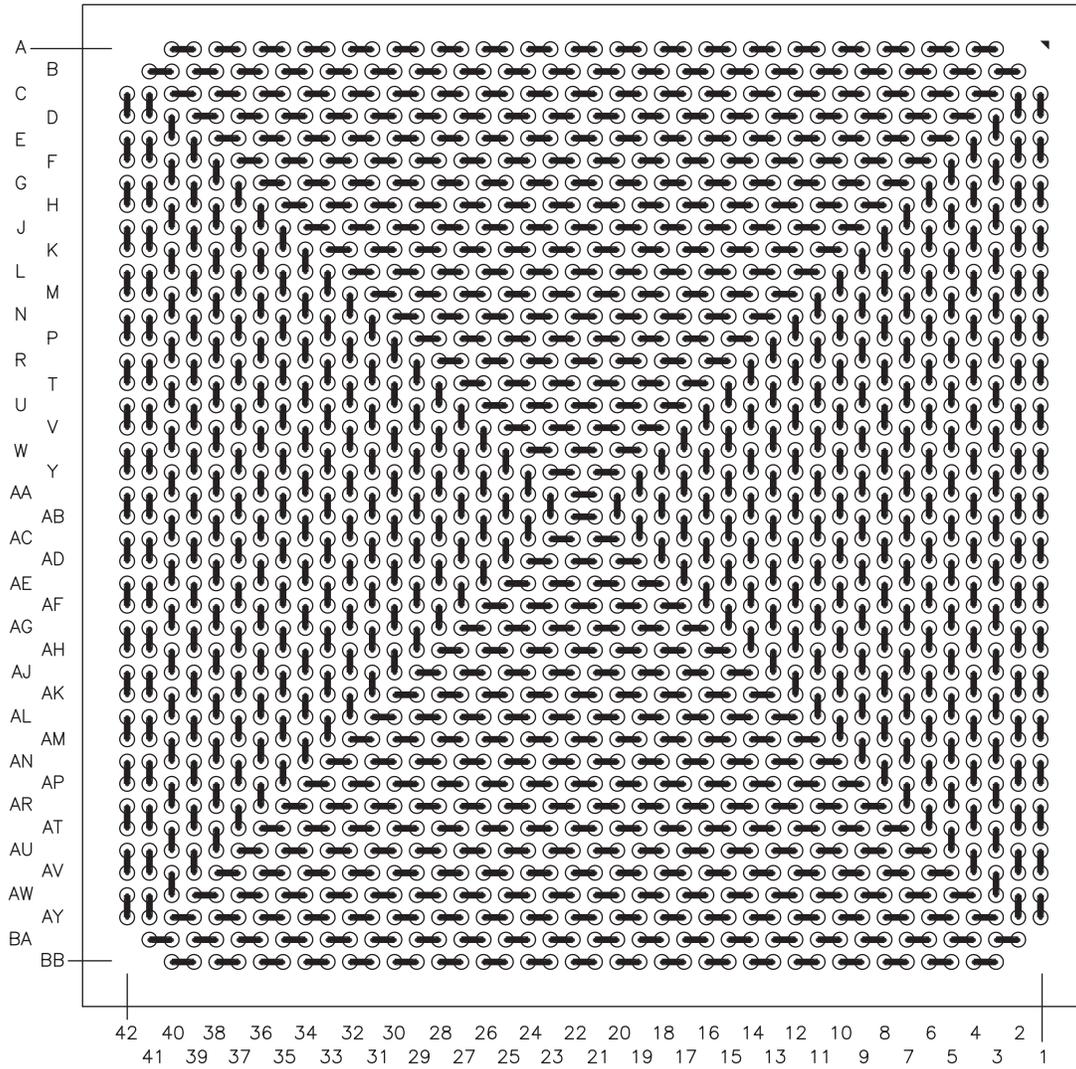


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Figure 4-3: CN1752 Ceramic Flip-Chip Column Grid Array Package Mechanical Drawing (45 mm × 45 mm Lid)

Note: The material used for the CN1752 lid is Nickel-plated Al-SiC, which is conductive and NOT connected to ground. For space environments, the Al-SiC lid should be connected to system ground.

CN1752 Daisy Chain Land Pattern



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Figure 4-4: CN1752 Daisy Chain Land Pattern